



SPECIFICATION (Reference sheet)

- Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor
- Samsung P/N : CL03C8R2BA3GNNH
- Description : CAP
- CAP, 8.2pF, 25V, ±0.1pF, C0G, 0201

A. Samsung Part Number

			<u>CL</u>	<u>03</u>	<u>C</u>	<u>8R2</u>	<u>B</u>	<u>A</u>	<u>3</u>	<u>G</u>	N	<u>N</u>	H	
			1	2	3	4	5	6	1	8	9	10	1	
1	Series	Samsung	a Multi-la	ver C	eran	nic Ca	oacit	or						
-	Size	0201	(inch co	•	-	-		± 0.0)3	mm		W:	0.3 ± 0.03	mm
3	Dielectric	COG	2				(8)	Inne	r ele	ctrod	<u> </u>		Cu	
4	Capacitance	8.2	-				U		nina		•		Cu	
5	Capacitance	±0.1	рF					Plat	ing				Sn 100%	(Pb Free)
	tolerance						9	Proc	duct				Normal	
6	Rated Voltage	25	V				10	Spe	cial				Reserved for	future use
\bigcirc	Thickness	0.3	± 0.03	mm			1	Pac	kagiı	ng			Cardboard Ty	/pe, 7" reel

B. Samsung Reliability Test and Judgement condition

	Performance	Test condition						
Capacitance	Within specified tolerance	1Mt±10% 0.5~5Vrms						
Q	564 min							
Insulation	More than 500Mohm⋅μF	Rated Voltage 60~120 sec.						
Resistance								
Appearance	No abnormal exterior appearance	Visual inspection						
Withstanding	No dielectric breakdown or	300% of the rated voltage						
Voltage	mechanical breakdown							
Temperature	COG							
Characteristics	(From -55℃ to 125℃, Capacitance change should be within ±30PPM/℃)							
Adhesive Strength	No peeling shall be occur on the	200g·F, for 10±1 sec.						
of Termination	terminal electrode							
Bending Strength	Capacitance change : within $\pm 0.5 pF$	Bending to the limit (1mm)						
		with 1.0mm/sec.						
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder						
	is to be soldered newly	245±5℃, 3±0.3sec.						
		(preheating : 80~120 ℃ for 10~30sec.)						
Resistance to	Capacitance change : within ±0.25 pF	Solder pot : 270±5℃, 10±1sec.						
Soldering heat	Tan δ, IR : initial spec.							

	Performance	Test condition				
Vibration Test	Capacitance change : within ±0.25pF	Amplitude : 1.5mm				
	Tan δ, IR : initial spec.	From $10Hz$ to $55Hz$ (return : 1min.)				
		2hours \times 3 direction (x, y, z)				
Moisture	Capacitance change : within ±0.75pF	With rated voltage				
Resistance	Q: 127.33 min	40±2℃, 90~95%RH, 500+12/-0 hours				
	IR : More than 25№ .µF					
High Temperature	Capacitance change : within ±0.3pF	With 200% of the rated voltage				
Resistance	Q : 282 min	Max. operating temperature				
	IR : More than 50№ μF	1000+48/-0 hours				
Temperature	Capacitance change : within ±0.25pF	1 cycle condition				
Cycling	Tan δ, IR : initial spec.	Min. operating temperature \rightarrow 25 °C				
		\rightarrow Max. operating temperature \rightarrow 25 °C				
		5 cycles test				

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5 °C, 10sec. Max)

Product specifications included in the specifications are effective as of March 1, 2013. Please be advised that they are standard product specifications for reference only. We may change, modify or discontinue the product specifications without notice at any time. So, you need to approve the product specifications before placing an order. Should you have any question regarding the product specifications, please contact our sales personnel or application engineers.